EIE

EIE Enterprise (M) Sdn. Bhd. (944691-T)

EIE ST 904-S Low VOC No-Clean Flux

DESCRIPTION

EIE ST 904-S is a Low VOC, Low solids, halide-free organic no-clean formulation designed for wave-soldering conventional and SMT boards assemblies. This formula is designed to provide the highest activity possible with combination of proprietary organics activators mixture, enhancing excellent wetting and top-side through-hole fill, even on *OSP coated bare copper boards*. With Low VOC solvent system, formula 904-S evaporative characteristics will reduce preheating time and splattering tendency, hence low solderball occurrence frequency. 904-S is formulated to maximize and enhanced solderability as priority with minimal post-soldering residue which is non-conductive, non-corrosive and does not need to be removed.

APPLICATION

EIE ST 904-S is specifically designed for spray or dip fluxing application. For spray fluxing application, air knife blow-away excess flux after spray is recommended to achieve flux uniformity. Flux coating of (450-1300) micrograms/sq inch is generally the optimal desired coating prior pre-heating. Typically it is recommended a preheated temperature of (95-105) °C as measured on the top/component side of the assembly board be achieved prior entry to wave-soldering.

PHYSICAL PROPERTIES

Appearance	Clear Straw
Specific Gravity @25°C	0.886 ± 0.005
Solids Content % (w/w)	3.8
Acid Number (mg KOH/g flux)	31.0 ± 2.0
Halide content	0
Flash Point (T.O.C.)	43°C
Silver Chromate Paper Test	Pass
IPC J-STD-004 Designation	ORL0

Surface Insulation Resistance
(As Per ANSI/J-STD-004, IPC-TM-650)

Day 4 (96 hrs) ohm	$>5.4 \times 10^{10}$
Day 7 (168 hrs) ohm	$>5.8 \times 10^{10}$
Minimum requirement (ohm)	1.0×10^{8}

STORAGE

Store in well ventilated, No direct sunshine environment

PACKING

25 litre/carboy